

**AP95N25W**

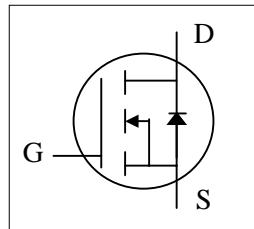
**RoHS-compliant Product**



**Advanced Power  
Electronics Corp.**

**N-CHANNEL ENHANCEMENT MODE  
POWER MOSFET**

- ▼ Simple Drive Requirement
- ▼ Lower On-resistance
- ▼ High Speed Switching

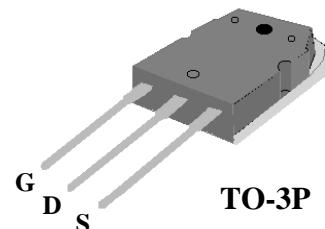


$BV_{DSS}$	250V
$R_{DS(ON)}$	55mΩ
$I_D$	50A

## Description

AP95N25 from APEC provide the designer with the best combination of fast switching , low on-resistance and cost-effectiveness .

The TO-3P package is preferred for commercial & industrial applications with higher power level preclusion than TO-220 device.



## Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	250	V
$V_{GS}$	Gate-Source Voltage	$\pm 30$	V
$I_D @ T_C = 25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V$	50	A
$I_{DM}$	Pulsed Drain Current <sup>1</sup>	200	A
$I_{DR}$	Body-Drain Diode Reverse Drain Current	50	A
$I_{DR(PULSE)}$	Body-Drain Diode Reverse Drain Peak Current <sup>1</sup>	200	A
$P_D @ T_C = 25^\circ C$	Total Power Dissipation	150	W
	Linear Derating Factor	1.2	W/°C
$I_{AR}$	Avalanche Current <sup>3</sup>	30	A
$T_{STG}$	Storage Temperature Range	-55 to 150	°C
$T_J$	Operating Junction Temperature Range	-55 to 150	°C

## Thermal Data

Symbol	Parameter	Value	Units
$R_{thj-c}$	Thermal Resistance Junction-case	Max.	0.833 °C/W
$R_{thj-a}$	Thermal Resistance Junction-ambient	Max.	40 °C/W



# AP95N25W

## Electrical Characteristics@ $T_j=25^\circ\text{C}$ (unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=1\text{mA}$	250	-	-	V
$R_{\text{DS}(\text{ON})}$	Static Drain-Source On-Resistance <sup>2</sup>	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=25\text{A}$	-	-	55	$\text{m}\Omega$
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\text{\mu A}$	2.5	-	4	V
$g_{\text{fs}}$	Forward Transconductance	$V_{\text{DS}}=10\text{V}, I_{\text{D}}=25\text{A}$	-	25	-	S
$I_{\text{DSS}}$	Drain-Source Leakage Current	$V_{\text{DS}}=250\text{V}, V_{\text{GS}}=0\text{V}$	-	-	1	$\text{\mu A}$
$I_{\text{GSS}}$	Gate-Source Leakage	$V_{\text{GS}}= \pm 30\text{V}, V_{\text{DS}}=0\text{V}$	-	-	$\pm 0.1$	$\text{\mu A}$
$Q_g$	Total Gate Charge <sup>2</sup>	$I_{\text{D}}=50\text{A}$	-	168	270	nC
$Q_{\text{gs}}$	Gate-Source Charge	$V_{\text{DS}}=200\text{V}$	-	36	-	nC
$Q_{\text{gd}}$	Gate-Drain ("Miller") Charge	$V_{\text{GS}}=10\text{V}$	-	68	-	nC
$t_{\text{d}(\text{on})}$	Turn-on Delay Time <sup>2</sup>	$V_{\text{DS}}=125\text{V}$	-	50	-	ns
$t_r$	Rise Time	$I_{\text{D}}=25\text{A}$	-	92	-	ns
$t_{\text{d}(\text{off})}$	Turn-off Delay Time	$R_{\text{G}}=10\Omega, V_{\text{GS}}=10\text{V}$	-	250	-	ns
$t_f$	Fall Time	$R_{\text{D}}=5\Omega$	-	105	-	ns
$C_{\text{iss}}$	Input Capacitance	$V_{\text{GS}}=0\text{V}$	-	8370	13400	pF
$C_{\text{oss}}$	Output Capacitance	$V_{\text{DS}}=15\text{V}$	-	1505	-	pF
$C_{\text{rss}}$	Reverse Transfer Capacitance	f=1.0MHz	-	60	-	pF

## Source-Drain Diode

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$V_{\text{SD}}$	Forward On Voltage <sup>2</sup>	$I_{\text{S}}=50\text{A}, V_{\text{GS}}=0\text{V}$	-	-	1.5	V
$t_{\text{rr}}$	Reverse Recovery Time <sup>2</sup>	$I_{\text{S}}=50\text{A}, V_{\text{GS}}=0\text{V}$	-	320	-	ns
$Q_{\text{rr}}$	Reverse Recovery Charge	$dI/dt=100\text{A}/\mu\text{s}$	-	4.7	-	$\mu\text{C}$

## Notes:

1.PW  $\leq 10\text{us}$ , duty cycle  $\leq 1\%$

2.Pulse test

3.STch =  $25^\circ\text{C}$  , Tch  $\leq 150^\circ\text{C}$

THIS PRODUCT IS AN ELECTROSTATIC SENSITIVE, PLEASE HANDLE WITH CAUTION.

THIS PRODUCT HAS BEEN QUALIFIED FOR CONSUMER MARKET. APPLICATIONS OR USES AS CRITERIAL COMPONENT IN LIFE SUPPORT DEVICE OR SYSTEM ARE NOT AUTHORIZED.

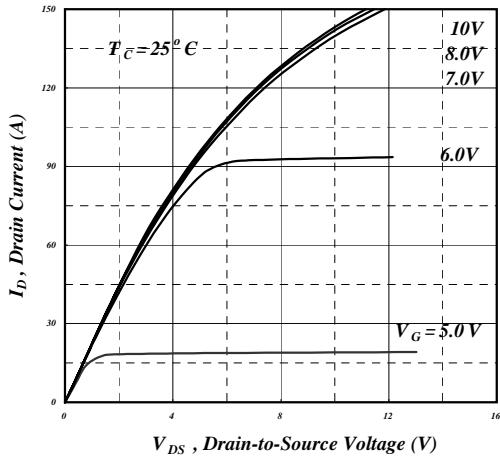


Fig 1. Typical Output Characteristics

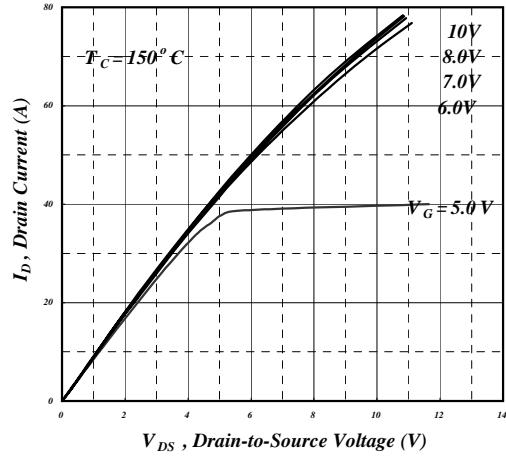


Fig 2. Typical Output Characteristics

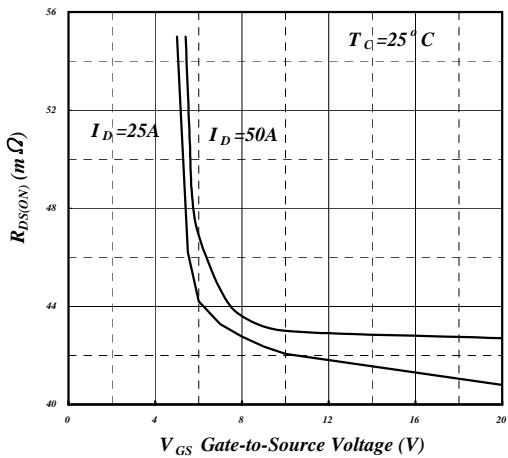


Fig 3. On-Resistance v.s. Gate Voltage

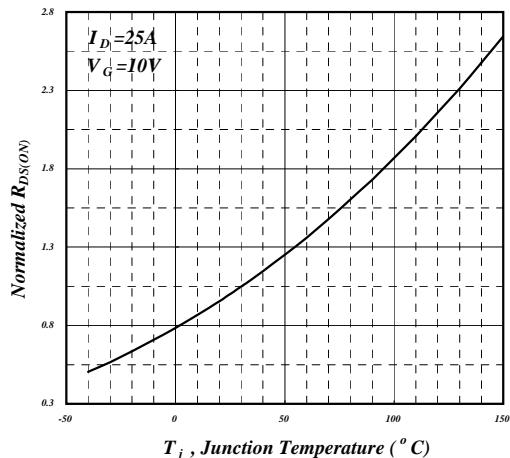


Fig 4. Normalized On-Resistance v.s. Junction Temperature

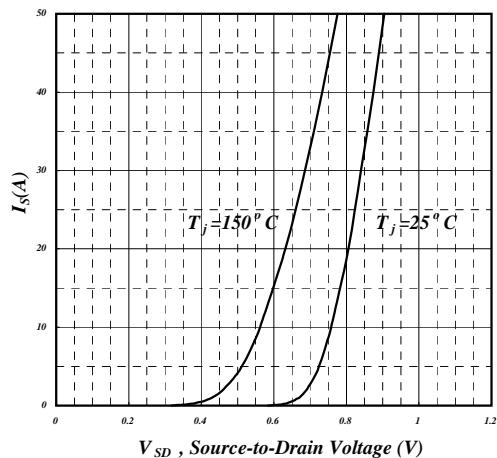


Fig 5. Forward Characteristic of Reverse Diode

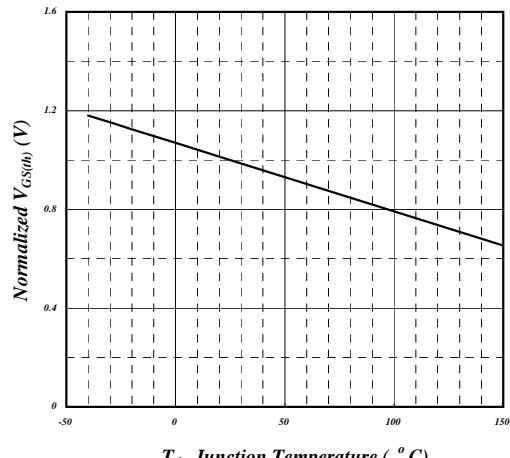


Fig 6. Gate Threshold Voltage v.s. Junction Temperature



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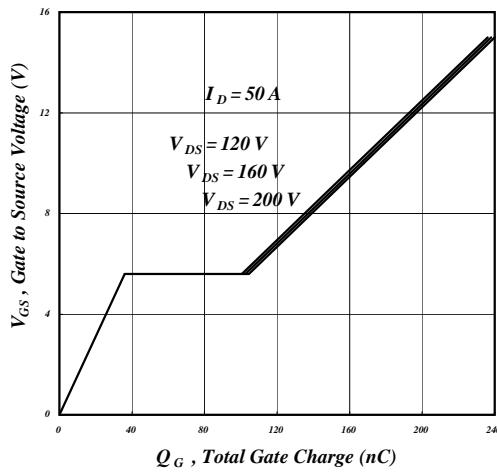


Fig 7. Gate Charge Characteristics

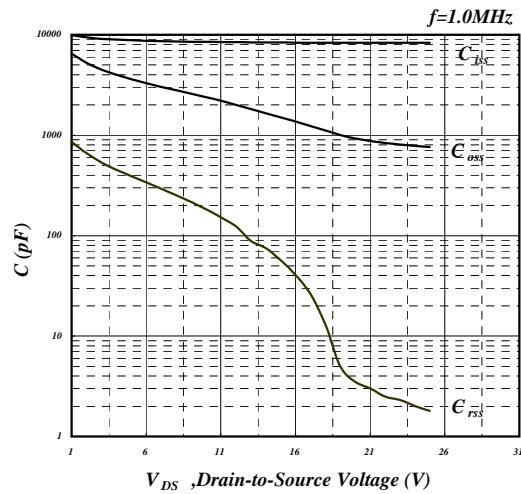


Fig 8. Typical Capacitance Characteristics

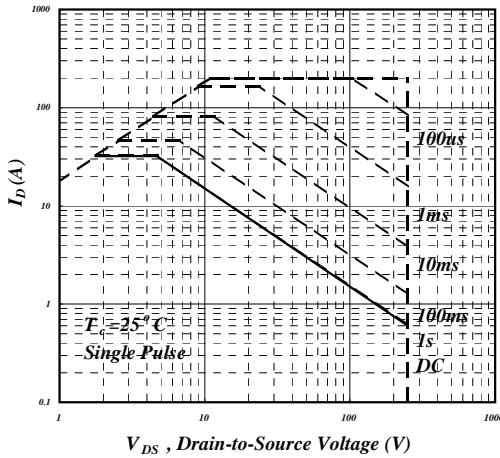


Fig 9. Maximum Safe Operating Area

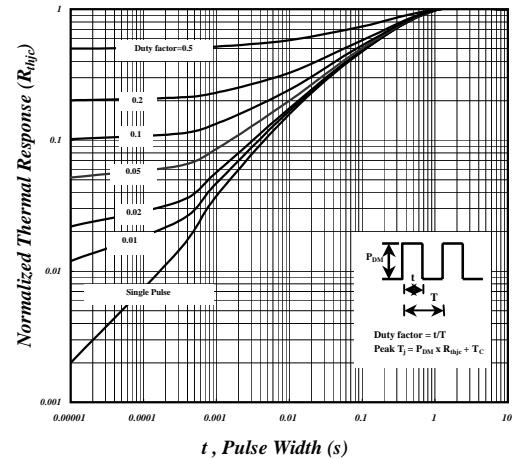


Fig 10. Effective Transient Thermal Impedance

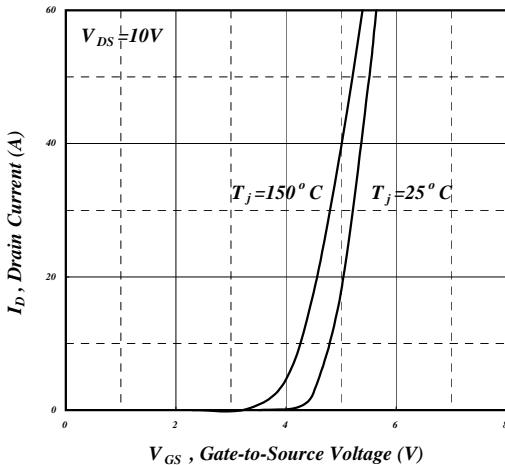


Fig 11. Transfer Characteristics

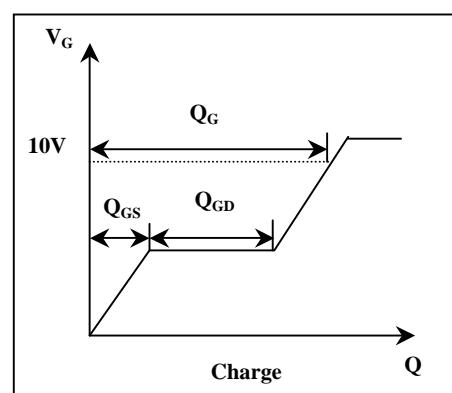


Fig 12. Gate Charge Waveform